

The documentation and process conversion measures necessary to comply with this amendment shall be completed by 16 January 2000.

INCH POUND

MIL-PRF-19500/350E  
AMENDMENT 1  
22 October 1999

PERFORMANCE SPECIFICATION SHEET

SEMICONDUCTOR DEVICE, TRANSISTOR, PNP, SILICON, LOW-POWER  
TYPES: 2N3867, 2N3867S, 2N3868, AND 2N3868S  
JAN, JANTX, JANTXV, JANS, JANHC, AND JANKC

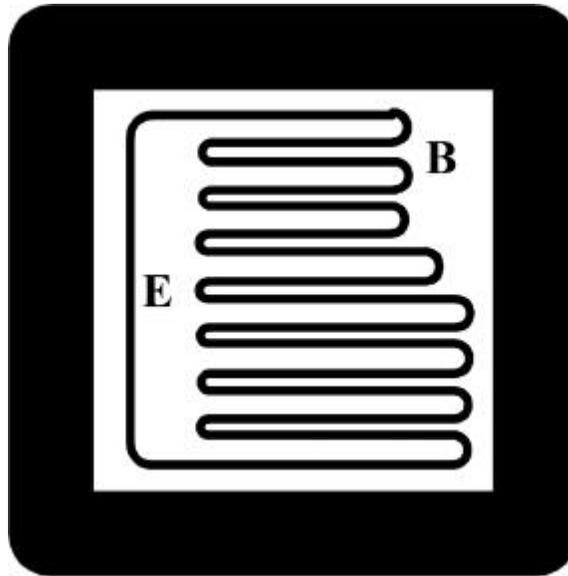
This amendment forms a part of MIL-PRF-19500/350E, dated 6 February 1999, and is approved for use by all Departments and Agencies of the Department of Defense.

PAGE 1

1.2, Physical dimensions, delete in its entirety, and substitute, "1.2 Physical dimensions. See figure 1 (similar to TO- 5) encapsulated devices, figure 2 and figure 4 for unencapsulated devices."

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Add figure 4:



- |                   |  |
|-------------------|--|
| 1. Chip size.     | 0.075 x 0.075 inches $\pm$ 0.002 inches  |
| 2. Chip thickness | 0.010 $\pm$ 0.0015 inches nominal  |
| 3. Top metal      | Aluminum 30,000Å minimum, 33,000Å nominal  |
| 4. Back metal     | A. Al/Ti/Ni/Ag 12kÅ/3kÅ/7kÅ/7kÅ minimal, 15kÅ/5kÅ/10kÅ/10kÅ nominal<br>B. Gold 2,500Å minimum, 3000Å nominal |
| 5. Backside       | Collector  |
| 6. Bonding pad    | B = 0.023 x 0.008 inches, E = 0.049 x 0.008 inches   |

FIGURE 4. JANHCB and JANKCB (B-version) die dimensions

AMSC N/A  
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4.3, Screening (JANS, JANTXV, and JANTX levels only), screen 9, under JANS, delete "l<sub>cb02</sub> and h<sub>FE4</sub>" and substitute "l<sub>CEX1</sub> and h<sub>FE2</sub>".

6.4, Suppliers of JANHC and JANKC die, delete in its entirety, and substitute,

"6.4 Suppliers of JANHC and JANKC die. The qualified JANHC and JANKC suppliers with the applicable letter version (example, JANHC2N3867) will be identified on the QPL.

JANC ordering information		
PIN	Manufacturer	
	33178	43611
2N3867	JANHCA2N3867 JANKCA2N3867	JANHCB2N3867 JANKCB2N3867
2N3868	JANHCA2N3868 JANKCA2N3868	JANHCB2N3868 JANKCB2N3868

"

CONCLUDING MATERIAL

Custodians:  
 Army - CR  
 Navy - EC  
 Air Force - 11  
 DLA-CC

Preparing activity:  
 DLA - CC

(Project 5961-2202)

Review activities:  
 Army - AR, AV, MI, SM  
 Navy - AS, CG, MC  
 Air Force - 13, 19, 99